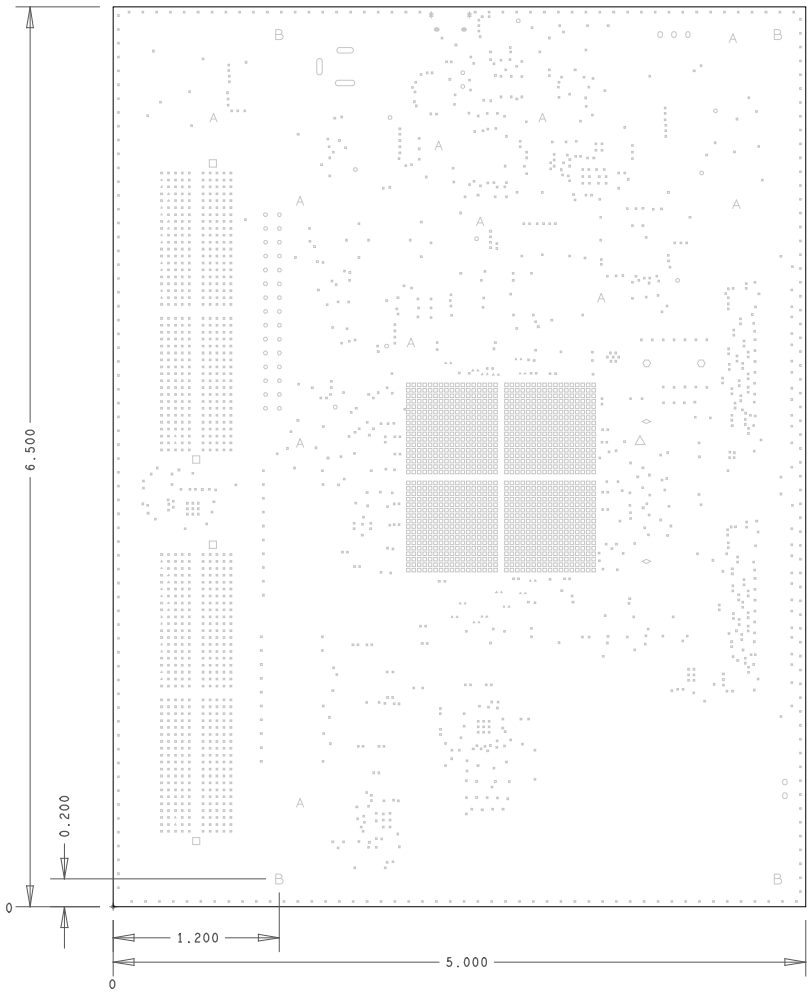
| DRILL CHART: TOP to BOTTOM<br>ALL UNITS ARE IN MILS | | | | |
|---|---|---|---|---|
| FIGURE | SIZE | TOLERANCE | PLATED | QTY |
| ▫ | 8.0 | +3.0/-8.0 | PLATED | 1156 |
| · | 12.0 | +3.0/-12.0 | PLATED | 1918 |
| · | 12.02 | +3.0/-12.0 | PLATED | 60 |
| ◦ | 21.654 | +2.0/-2.0 | PLATED | 6 |
| · | 21.654 | +3.0/-3.0 | PLATED | 8 |
| ◦ | 28.0 | +3.0/-3.0 | PLATED | 41 |
| ○ | 42.0 | +3.0/-3.0 | PLATED | 5 |
| A | 63.0 | +3.0/-3.0 | PLATED | 11 |
| △ | 67.0 | +3.0/-3.0 | PLATED | 1 |
| ◇ | 138.0 | +3.0/-3.0 | PLATED | 2 |
| ○ | 40.0 | +3.0/-3.0 | NON-PLATED | 2 |
| □ | 52.0 | +3.0/-3.0 | NON-PLATED | 4 |
| B | 125.0 | +3.0/-3.0 | NON-PLATED | 4 |
| ▭ | 118.11x40.0 | +2.99/-2.99 | PLATED | 1 |
| ▯ | 118.11x40.0 | +2.99/-2.99 | PLATED | 1 |
| ▭ | 140.0x40.0 | +2.99/-2.99 | PLATED | 1 |

7.




FAB NOTES:

1. ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE NOTED. ALL BOARD OUTLINE DIMENSION TOLERANCES ARE +/- .010". DIMENSIONS ARE FOR REFERENCE ONLY - USE ARTWORK FOR ACCURATE MEASUREMENT OF THE BOARD OUTLINE.
2. THE PWB SHALL BE FABRICATED TO IPC-6011 AND IPC-6012, CLASS 2, TYPE 3. WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2. CURRENT REVISIONS.
3. BOARD MATERIAL SHALL BE NELCO SI OR EQUIVALENT. RoHS COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B. RoHS CERTIFICATE OF CONFORMANCE SHALL BE DELIVERED WITH EACH LOT.
4. BOARD MATERIAL & CONSTRUCTION TO BE U.L. APPROVED AND MARKED ON THE FINISHED BOARD. MARK EFILE NUMBER ON THE FINISHED BOARD.
5. MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH, WITH A MINIMUM ANNULAR RING OF .001 INCH.
6. OVERALL BOARD THICKNESS TO BE .062 +/- 10% AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.
7. INNER PLANE LAYERS TO BE 1/2 OZ. COPPER. INNER SIGNAL LAYERS TO BE 1/2 OZ. COPPER. OUTER LAYERS TO BE 1/2 OZ. COPPER + PLATING.
8. MAX. WARP & TWIST TO BE .0075 INCHES PER INCH.
9. MAXIMUM RATED VOLTAGE BETWEEN CONDUCTORS SHALL BE 65 VOLTS PEAK.
10. NO BREAKOUT ALLOWED ON PLATED THROUGH HOLES.
11. FOIL OUTER OPTIONAL.
12. INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5M-1994
13. TEARDROP VIAS AS NECESSARY.
14. THIEVING IS NOT ALLOWED.

PROCESS NOTES:

1. EXCEPT AS NOTED BELOW, ALL EXPOSED CONDUCTORS ON BOTH SIDES PWB SHALL BE ELECTROPLATED GOLD (5-15 MICROINCHES) OVER ELECTROPLATED NICKEL (50 MIN MICROINCHES).
2. APPLY LPI SOLDERMASK. COLOR: RED. SOLDERMASK SHALL CONFORM TO IPC-SM-840, CLASS H. CURRENT REV.
3. FABRICATION VENDOR IS ALLOWED TO INCREASE SOLDERMASK COMPONENT PADS BY A MAXIMUM 1 MIL ON EACH SIDE OVER THE COPPER PAD IN ORDER TO MEET TOOLING REQUIREMENTS WHILE MAINTAINING WEBBING BETWEEN ADJACENT PADS.
4. APPLY LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK BOTH SIDES. COLOR: WHITE.
5. BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.
6. ~~PLATE INDICATED PAD AREAS WITH A MINIMUM OF 30, MAXIMUM OF 50 MICROINCHES ELECTROLYTIC HARD GOLD OVER A MINIMUM OF 50 MICROINCHES OF ELECTROLYTIC NICKEL.~~
7. BACKDRILL 12.02 VIAS FROM TOP SIDE TO LAYER 7 (CONNECTIONS ARE ON LAYER 8 AND 10).

Primary Side Shown

| TEXAS INSTRUMENTS | | |
|---|---|---|
| BOARD NAME: DLP019A | DESCRIPTION: FAB DRAWING | |
| PROJECT #: DLP-30177-04 | DATE: 18 JAN 2021 | REVISION: |

LAYER STACKUP

LAYER 1 - PRIMARY SIDE
LAYER 2 - GND PLANE
LAYER 3 - SIGNAL
LAYER 4 - GND PLANE
LAYER 5 - PWR PLANE
LAYER 6 - PWR PLANE
LAYER 7 - GND PLANE
LAYER 8 - SIGNAL
LAYER 9 - GND PLANE
LAYER 10 - SECONDARY SIDE

CONTROLLED IMPEDANCE

EXTERNAL LAYERS

0.0055" WIDE 50 OHMS SINGLE ENDED +/-10%
0.0039" WIDE/0.0056" SPACING 100 OHMS DIFFERENTIAL +/-10%

INTERNAL LAYERS

0.00475" WIDE 50 OHMS SINGLE ENDED +/-10%
0.0045" WIDE/0.077" SPACING 100 OHMS DIFFERENTIAL +/-10%